

# SML0606-UY/UG-TR

Yellow/Green

Surface Mount LED

1.6 × 1.5 × 0.8 mm Chip LED

140° viewing angle

DWG BY:  
SL / GP  
08-13-07

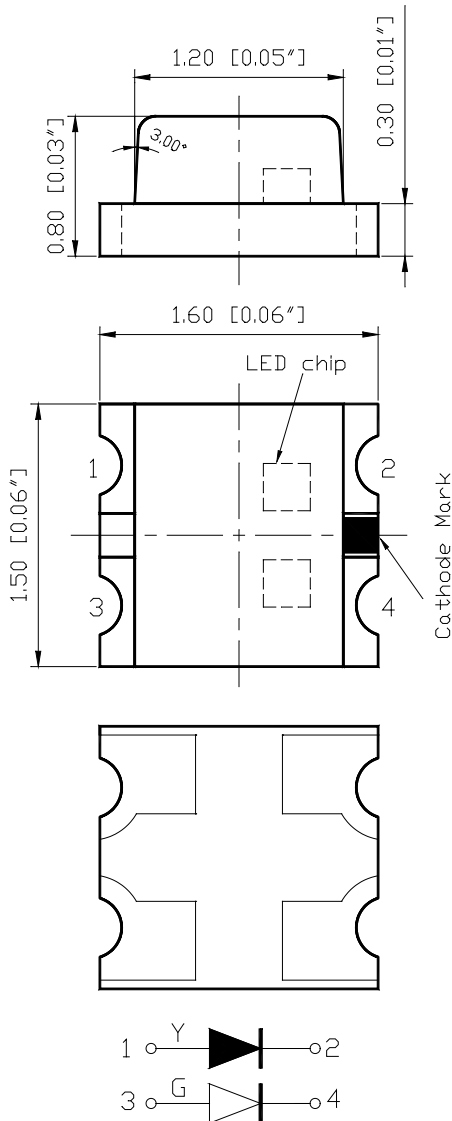
CHK BY:  
PL  
08-15-07

QA:  
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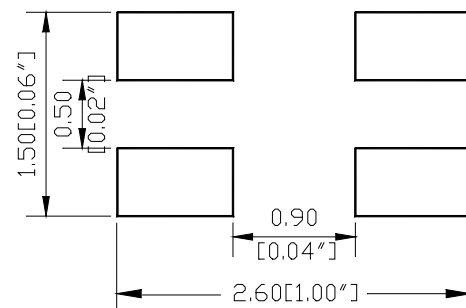
MFG:  
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REVISION LTR: -  
08-13-07

## Package outlines



### RECOMMEND PAD LAYOUT



| ITEM                  | MATERIALS         |         |
|-----------------------|-------------------|---------|
| Resin (mold)          | Epoxy             |         |
| Bonding Wire          | Ø25µm Au          |         |
| Lens color            | Water Transparent |         |
| Printed circuit board | BT (White)        |         |
| Dice                  | Yellow            | AlGaInP |
|                       | Green             | AlGaInP |

### NOTES:

- All dimensions are in millimeters (inches);
- Tolerance are ±0.1mm (0.004inch) unless otherwise noted.

**Absolute maximum ratings (T<sub>A</sub>=25°C)**

| Parameter                              | Symbol | Value    |    | Unit |
|--|--------|----------|----|------|
|  |        | Y        | G  |      |
| Power dissipation                      | Pd     | 75       | 75 | mW   |
| Forward current                        | If     | 30       |    | mA   |
| Reverse voltage                        | Vr     | 5        |    | V    |
| Operating temperature range            | Top    | -20 ~+80 |    | °C   |
| Storage temperature range              | Tstg   | -20~+80  |    | °C   |
| Peak pulsing current (1/8 duty f=1kHz) | Ifp    | 125      |    | mA   |

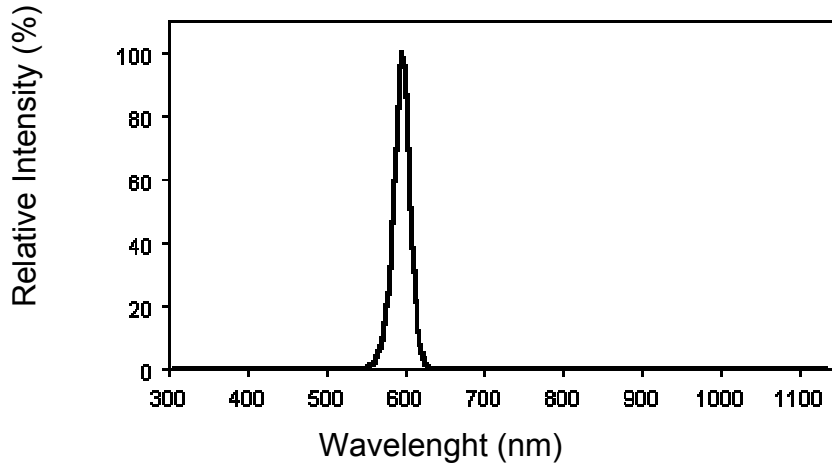
**Electro-optical characteristics (T<sub>A</sub>=25°C)**

| Parameter                   | Test Condition | Symbol   | Value |       |     | Unit   |
|-----------------------------|----------------|----------|-------|-------|-----|--------|
|                             |                |          | Min   | Typ   | Max |        |
| Wavelength at peak emission | If=20mA        | λ peak Y | --    | 592   | --  | nm     |
|                             |                | G        | --    | 575   | --  |        |
| Spectral half bandwidth     | If=20mA        | Δλ Y     | --    | 19    | --  | nm     |
|                             |                | G        | --    | 17    | --  |        |
| Dominant wavelength         | If=20mA        | λ dom Y  | --    | 589   | --  | nm     |
|                             |                | G        | --    | 573   | --  |        |
| Forward voltage             | If=20mA        | Vf Y     | --    | 2.0   | 2.6 | V      |
|                             |                | G        | --    | 2.1   | 2.6 |        |
| Luminous intensity * 1      | If=20mA        | Iv Y     | --    | 100.0 | --  | mcd    |
|                             |                | G        | --    | 45.0  | --  |        |
| Viewing angle at 50% Iv     | If=10mA        | 2θ 1/2   | --    | 140   | --  | Deg    |
| Reverse current             | Vr=5V          | Ir       | --    | --    | 10  | μA     |
| Chromaticity Coordinates    | If=20mA        | X        | --    | 0.57  | --  | Yellow |
|                             |                | Y        | --    | 0.42  | --  |        |
| Chromaticity Coordinates    | If=20mA        | X        | --    | 0.47  | --  | Green  |
|                             |                | Y        | --    | 0.52  | --  |        |

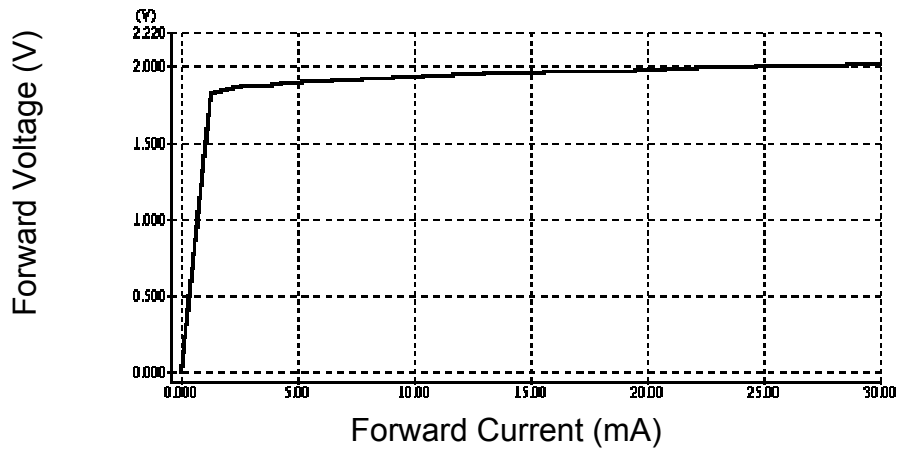
\* 1 Note: Luminous intensity tolerance is ±10%.

## OPTICAL CHARACTERISTIC CURVES (Yellow)

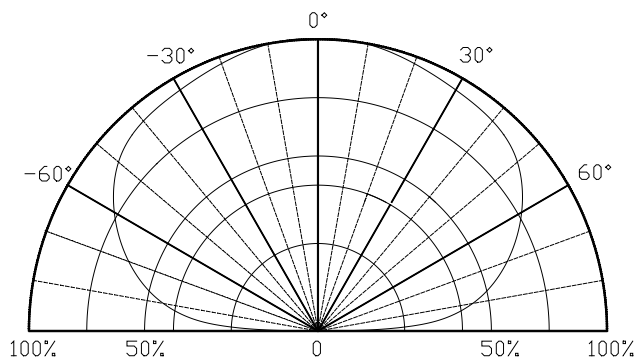
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage

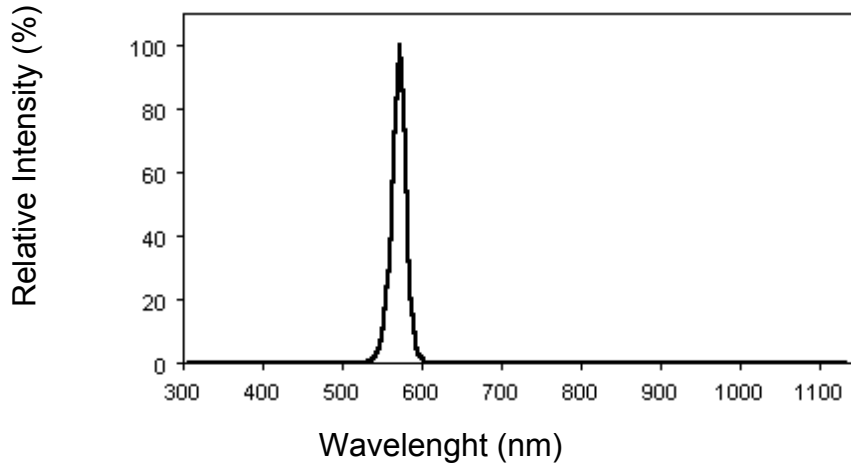


Directive Characteristics

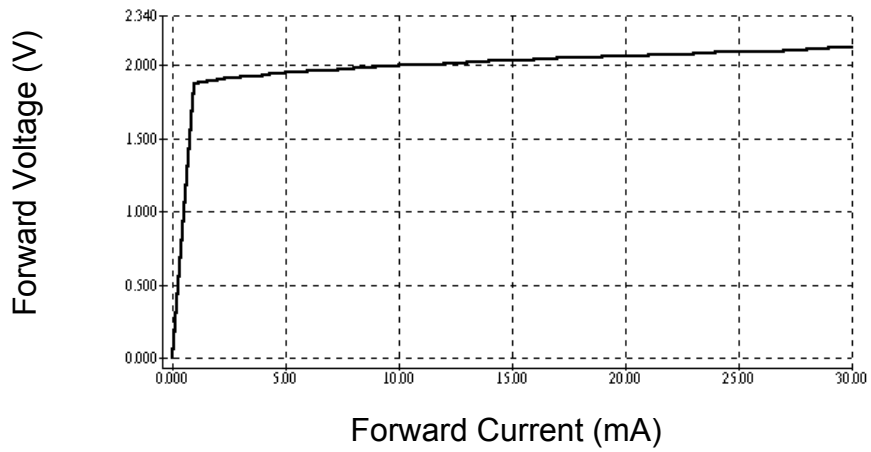


## OPTICAL CHARACTERISTIC CURVES (Green)

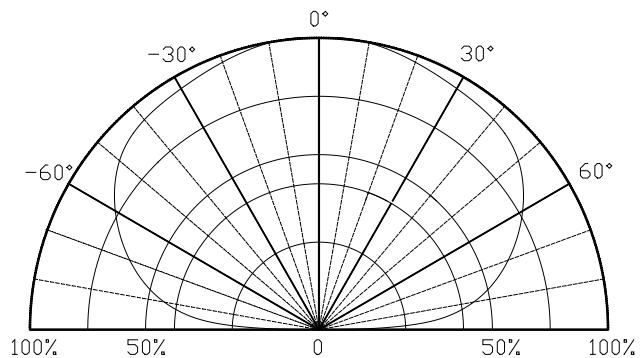
Relative Intensity vs. Wavelength



Forward Current vs. Forward Voltage

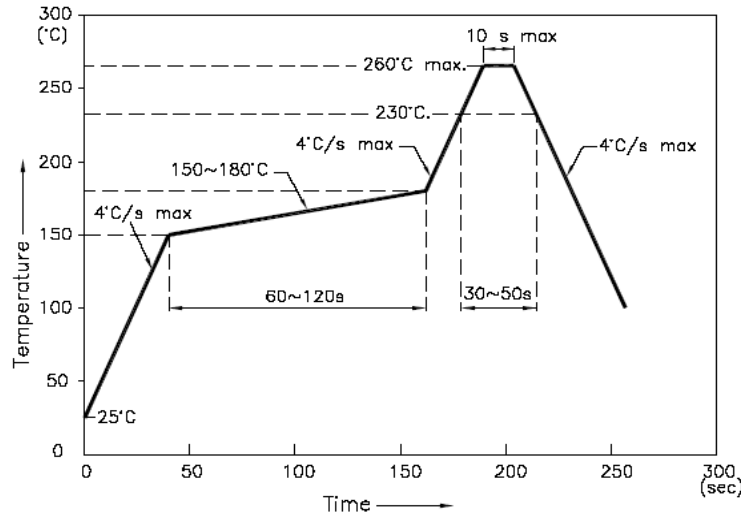


Directive Characteristics



## Reflow Profile

### ■ Reflow Temp/Time



### NOTES:

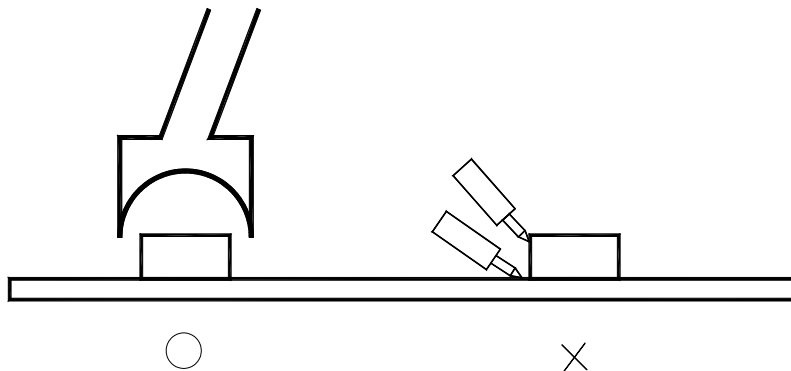
1. We recommend the reflow temperature  $245^{\circ}\text{C} (\pm 5^{\circ}\text{C})$ . the maximum soldering temperature should be limited to  $260^{\circ}\text{C}$ .
2. dont cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

### ■ Soldering iron

Basic spec is  $\leq 5\text{sec}$  when  $260^{\circ}\text{C}$ . If temperature is higher, time should be shorter ( $+10^{\circ}\text{C} \rightarrow -1\text{sec}$ ). Power dissipation of iron should be smaller than 15W, and temperatures should be controllable. Surface temperature of the device should be under  $230^{\circ}\text{C}$ .

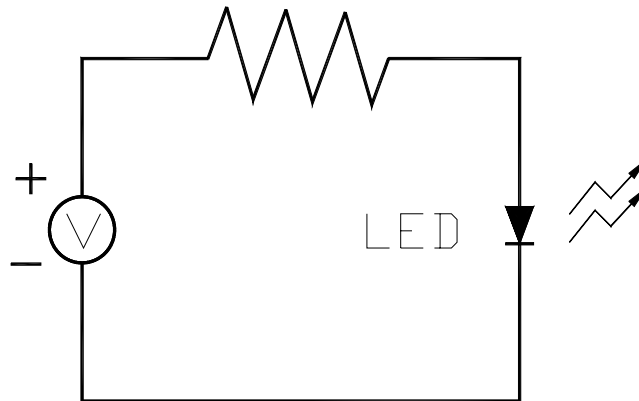
### ■ Rework

1. Customer must finish rework within 5 sec under  $260^{\circ}\text{C}$ .
2. The head of iron can not touch copper foil
3. Twin-head type is preferred.



## Test circuit and handling precautions

### ■ Test circuit



### ■ Handling precautions

#### 1. Over-current-proof

Customer must apply resistors for protection; otherwise slight voltage shift will cause big current change (Burn out will happen).

#### 2.Storage

2.1 It is recommended to store the products in the following conditions:

Humidity: 60% R.H. Max.

Temperature : 5°C~30°C (41°F~86°F)

2.2 Shelf life in sealed bag: 12 month at <5°C~30°C and <30% R.H. after the package is Opened, the products should be used within a week or they should be keeping to stored at  $\leq 20$  R.H. with zip-lock sealed.

#### 3.Baking

It is recommended to baking before soldering when the pack is unsealed after 72hrs. The Conditions are as followings:

3.1 60±3°C x(12~24hrs) and <5%RH, taped reel type

3.2 100±3°C x(45min~1hr), bulk type

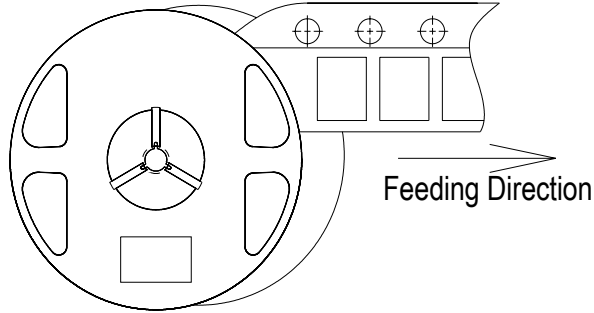
3.3 130±3°C x(15~30min), bulk type

**Test items and results of reliability**

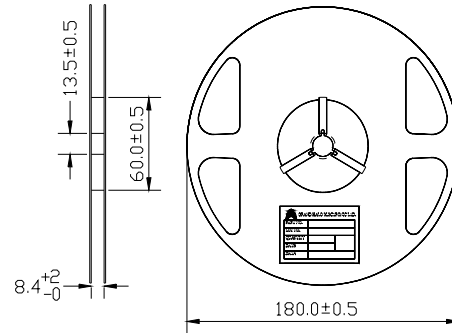
| Type                   | Test Item                    | Test Conditions                               | Note      | Number of Damaged |
|------------------------|------------------------------|---|-----------|-------------------|
| Environmental Sequence | Temperature Cycle            | -20°C 30min<br>↑ ↓<br>80°C 30min              | 100 cycle | 0/22              |
|                        | Thermal Shock                | -20°C 15min<br>↑ ↓<br>80°C 15min              | 100 cycle | 0/22              |
|                        | High Humidity Heat Cycle     | 30°C ↔ 65°C<br>90%RH 24hrs/1cycle             | 10 cycle  | 0/22              |
|                        | High Temperature Storage     | T <sub>a</sub> =80°C                          | 1000 hrs  | 0/22              |
|                        | Humidity Heat Storage        | T <sub>a</sub> =60°C<br>RH=90%                | 1000 hrs  | 0/22              |
|                        | Low Temperature Storage      | T <sub>a</sub> =-30°C                         | 1000 hrs  | 0/22              |
| Operation Sequence     | Life Test                    | T <sub>a</sub> =25°C<br>I <sub>F</sub> =20mA  | 1000 hrs  | 0/22              |
|                        | High Humidity Heat Life Test | 60°C RH=90%<br>I <sub>F</sub> =10mA           | 500 hrs   | 0/22              |
|                        | Low Temperature Life Test    | T <sub>a</sub> =-20°C<br>I <sub>F</sub> =20mA | 1000 hrs  | 0/22              |

# LED Lamps Packaging Specifications

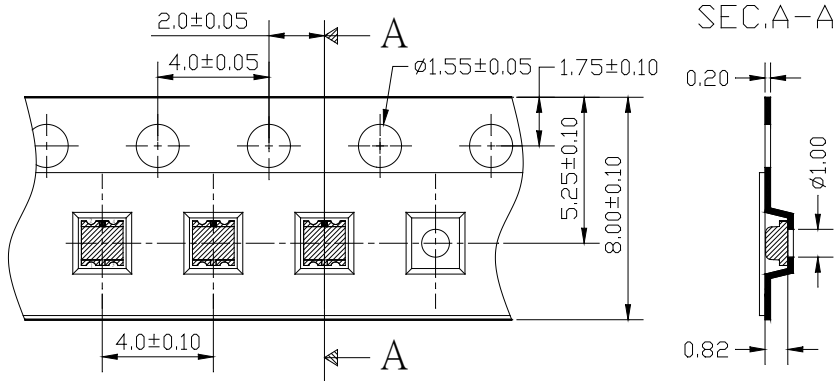
## ● Feeding Direction



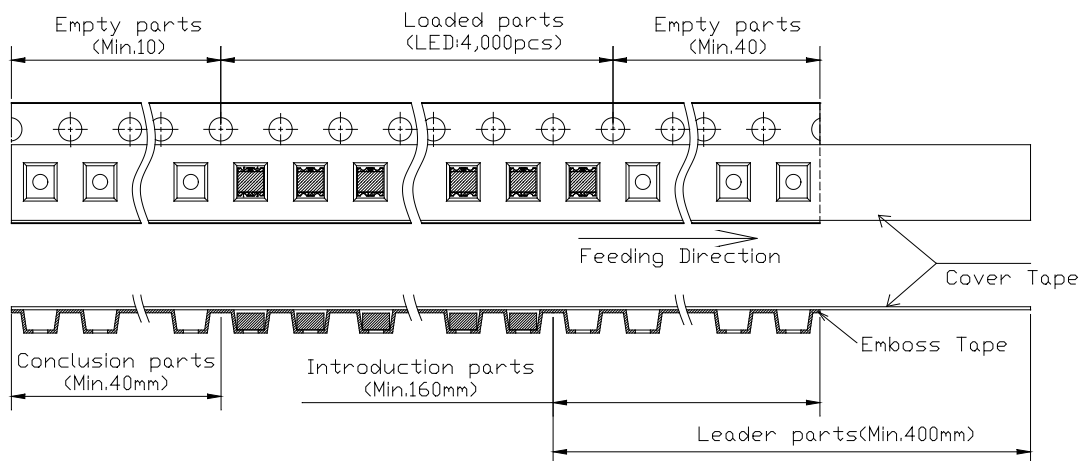
## ● Dimensions of Reel (Unit: mm)



## ● Dimensions of Tape (Unit: mm)



## ● Arrangement of Tape



### NOTES

1. Empty component pockets are sealed with top cover tape;
2. The maximum number of missing lamps is two;
3. 4,000pcs/Reel